

S2L-SMT 3.50/06/90 3.2SN BK BX**Weidmüller Interface GmbH & Co. KG**

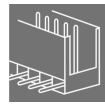
Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com**Product image**

Similar to illustration

Do not use product for new developments

High-temperature-resistant, straight, 2-tier pin header for all common soldering methods. Optimized for automatic assembly. Packed in box or tape. 3.2 mm solder pin suitable for reflow and wave soldering. These pin headers can be labelled and coded. (Packaging in tape on request)

General ordering data

Version	PCB plug-in connector, male header, open side, THT/THR solder connection, 3.50 mm, Number of poles: 6, 90°, Solder pin length (l): 3.2 mm, tinned, black, Box
Order No.	1794370000
Type	S2L-SMT 3.50/06/90 3.2SN BK BX
GTIN (EAN)	4032248231553
Qty.	174 pc(s).
Product data	IEC: 160 V / 10 A UL: 150 V / 10 A
Packaging	Box
Delivery status	This article will no longer be available in the future.
Available until	2028-12-31
Creation date	April 22, 2025 12:23 PM CEST

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Technical data**Dimensions and weights**

Depth	14.2 mm	Depth (inches)	0.559 inch
Height	14 mm	Height (inches)	0.551 inch
Height of lowest version	10.8 mm	Width	10.5 mm
Width (inches)	0.413 inch	Net weight	1.76 g

System specifications

Product family	OMNIMATE Signal - series B2L/S2L 3.50 - 2-row	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.5 mm
Pitch in inches (P)	0.138 "	Outgoing elbow	90°
Number of poles	6	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin dimensions	d = 1.0 mm, Octagonal
Solder eyelet hole diameter (D)	1.3 mm	Solder eyelet hole diameter tolerance (D) + 0,1 mm	
Outside diameter of solder pad	2.1 mm	Template aperture diameter	1.9 mm
L1 in mm	7 mm	L1 in inches	0.276 "
Number of rows	2	Pin series quantity	2
Touch-safe protection acc. to DIN VDE 57 106	finger-safe unplugged/ back-of-hand-safe plugged	Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 unplugged
Can be coded	Yes	Plugging force/pole, max.	3 N
Pulling force/pole, max.	6 N		

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIb
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Cu-alloy
Contact surface	tinned	Layer structure of solder connection	2...3 µm Ni / 5...7 µm Sn glossy
Layer structure of plug contact	2...5 µm Sn / 1...3 µm Ni	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	10 A
Rated current, max. number of poles (Tu=20°C)	10 A	Rated current, min. number of poles (Tu=40°C)	9 A
Rated current, max. number of poles (Tu=40°C)	8.5 A	Rated voltage for surge voltage class / pollution degree II/2	160 V
Rated voltage for surge voltage class / pollution degree III/2	125 V	Rated voltage for surge voltage class / pollution degree III/3	50 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	1.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	1.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 77 A

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Technical data**Rated data acc. to CSA**

Institute (CSA)



Certificate No. (CSA)

200039-1176845

Rated voltage (Use group B / CSA)	150 V
Rated voltage (Use group D / CSA)	150 V
Rated current (Use group C / CSA)	9.5 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.

Rated voltage (Use group C / CSA)	50 V
Rated current (Use group B / CSA)	5 A
Rated current (Use group D / CSA)	9.5 A

Rated data acc. to UL 1059

Institute (UR)



Certificate No. (UR)

E60693

Rated voltage (Use group B / UL 1059)	150 V
Rated current (Use group B / UL 1059)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.

Rated voltage (Use group C / UL 1059)	50 V
Rated current (Use group C / UL 1059)	10 A

Packing

Packaging	Box	VPE length	352 mm
VPE width	137 mm	VPE height	25 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ETIM 10.0	EC002637	ECLASS 9.0	27-44-04-02
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01	ECLASS 12.0	27-46-02-01
ECLASS 13.0	27-46-02-01	ECLASS 14.0	27-46-02-01
ECLASS 15.0	27-46-02-01		

Environmental Product Compliance

RoHS Compliance Status	Compliant without exemption
REACH SVHC	No SVHC above 0.1 wt%

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Technical data**Important note**

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	• Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Spacing between rows: see hole layout • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet $D = 1.3 \pm 0.1$ mm • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • In accordance with IEC 61984, OMNIMATE-connectors are connectors without breaking capacity (COC). During designated use, connectors are not allowed to be engaged or disengaged when live or under load • Long term storage of the product with average temperature of 50 °C and maximum humidity 70%, 36 months

Approvals

Approvals



Approvals MAMID	https://mdcop.weidmueller.com/mediadelivery/rendition/900_319226/-T1z1mm-S800/ https://mdcop.weidmueller.com/mediadelivery/rendition/900_319262/-T1z1mm-S800/
ROHS	Conform
UL File Number Search	UL Website
Certificate No. (UR)	E60693

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Technical data

Downloads

Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Engineering Data	CAD data – STEP
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN
	MB SMT EN
	FL DRIVES DE
	MB DEVICE MANUF. EN
	FL BUILDING SAFETY EN
	FL APPL LED LIGHTING EN
	FL INDUSTR.CONTROLS EN
	FL MACHINE SAFETY EN
	FL HEATING ELECTR EN
	FL APPL INVERTER EN
	FL_BASE_STATION_EN
	FL ELEVATOR EN
	FL POWER SUPPLY EN
	FL 72H SAMPLE SER EN
	PO OMNIMATE EN
White paper surface mount technology	Download Whitepaper

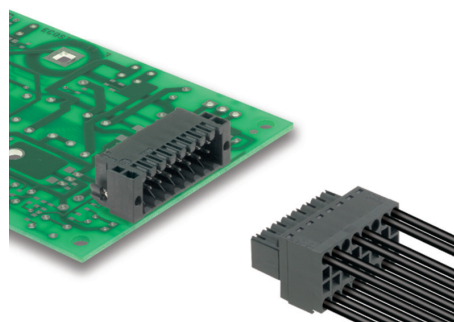
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Drawings

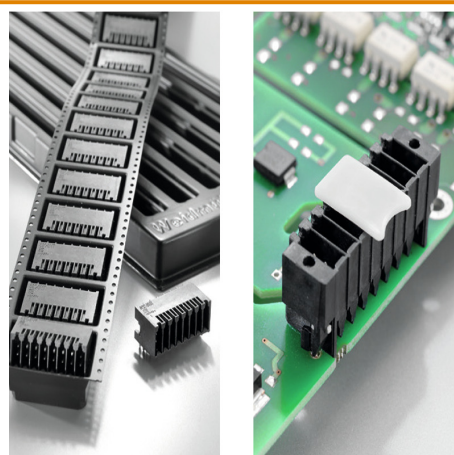
Example of use



Example of use

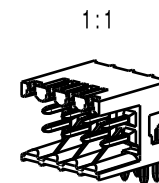
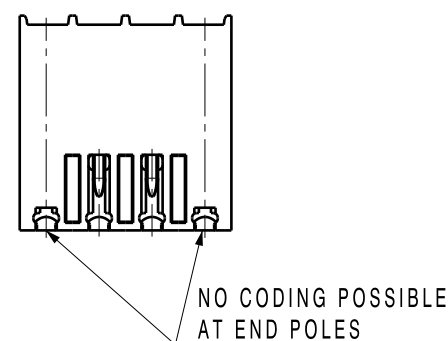


Product benefits



Optimised for the SMT process
Safe board-to-board connection

 WEIDMÜLLER INTERFACE GmbH & Co. KG



36	59,50	2,343
34	56,00	2,205
32	52,50	2,067
30	49,00	1,929
28	45,50	1,791
26	42,00	1,654
24	38,50	1,516
22	35,00	1,378
20	31,50	1,240
18	28,00	1,102
16	24,50	0,965
14	21,00	0,827
12	17,50	0,689
10	14,00	0,551
8	10,50	0,413
6	7,00	0,276
4	3,50	0,138
n	L1 [mm]	L1 [inch]

Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application. Provided that the components are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

 DIN ISO 2768					CAT.NO.: .	
	80058/3	19.01.15 HELIS_MA	01	Weidmüller 		C 32283 26
	MODIFICATION					DRAWING NO.
					SHEET 01	OF 03 SHEETS
		DATE	NAME	S2L-SMT 3.50/.../90... STIFTELEISTE MALE HEADER		
	DRAWN	19.03.2007	LANG_T			
	RESPONSIBLE		AMANN_A			
SCALE: 2/1	CHECKED	21.01.2015	HERTEL_S	PRODUCT FILE: S2L-SMT 3.50 7272		
SUPERSEDES: .	APPROVED		LANG_T			

Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
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Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com

Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260 °C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.